

## Lead-Free Production Policy

D/QA/Pb-Free/1 2005



CML is committed to providing Pb-free products suitable for its customers' requirements.

In line with the requirements of the Waste Electrical and Electronic Equipment (WEEE) and Restriction of Hazardous Substances (RoHS) directives, and its commitment to obtaining ISO14001, CML announces that, as from January 1<sup>st</sup> 2005 it will not guarantee that parts use Pb in the lead-plating finish. Current Pb-inclusive lead plating will be phased-out and replaced mainly by a pure matte Sn finish\*.

This decision relates purely to the removal of Pb from lead finish. Pure matte Sn has been chosen by CML due to its history of reliable performance in Sn-Pb lead soldering processes and its compatibility with Pb-free soldering. CML has carried out extensive research to determine that our Pb-free devices perform at standard Sn-Pb reflow temperatures.

CML has an on-going testing programme to evaluate its product range at the higher reflow soldering temperatures associated with full Pb-free assembly. Please ask specifically for Pb-free parts if you require full Pb-free compatible processing capability.

\* LS/L2 parts will use Sn-Ag lead finish.

Pb: Lead Sn :Tin Ag: Silver